

CLAIMS

What is claimed is:

- 1 1. A device enclosure comprising:
2 a thermo-siphon device embedded in an enclosure skin.
- 1 2. The device of claim 1, wherein the device is an electronic
2 device.
- 1 3. The device of claim 2, wherein the device enclosure is a
2 computer chassis.
- 1 4. The device of claim 1, wherein the device is a non-
2 electronic device.
- 1 5. The device of claim 1, wherein the thermo-siphon device is
2 a heat pipe.
- 1 6. The device of claim 1, wherein the thermo-siphon device is
2 a strip of a high efficiency conduit material.
- 1 7. The device of claim 1, wherein the thermo-siphon device is
2 an integral part of the skin.
- 1 8. The device of claim 7, wherein the thermo-siphon device is
2 embedded in the skin during the manufacturing process of the skin.
- 1 9. The device of claim 1, wherein the skin is fabricated from a
2 metallic material.

1 20. The system of claim 19, wherein the thermo-siphon device
2 is a heat pipe.

1 21. The system of claim 19, wherein the thermo-siphon device
2 is a strip of high efficiency conduit material.

1 22. The system of claim 19, wherein the housing is a computer
2 chassis.

1 23. The system of claim 19, wherein the thermo-siphon device
2 is an integral part of the housing skin.

1 24. A computer chassis comprising:
2 a thermo-siphon device embedded in a computer chassis
3 skin.

1 25. The computer chassis of claim 24, wherein the thermo-
2 siphon device is a heat pipe.

1 26. The computer chassis of claim 24, wherein the computer
2 chassis is a notebook computer base.

1 27. The computer chassis of claim 24, wherein the thermo-
2 siphon device is an integral part of the skin.

